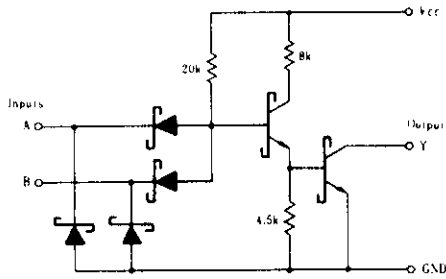
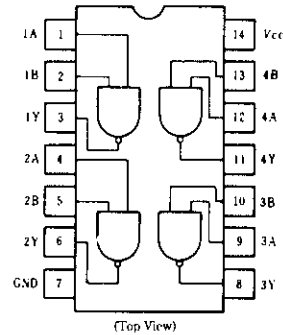


HD74LS26 ● Quadruple 2-input High-voltage Interface Positive NAND Gates

■ CIRCUIT SCHEMATIC (1/4)



■ PIN ARRANGEMENT



■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output voltage	V_{OH}	—	—	15	V
Low level output current	I_{OL}	—	—	8	mA

■ ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

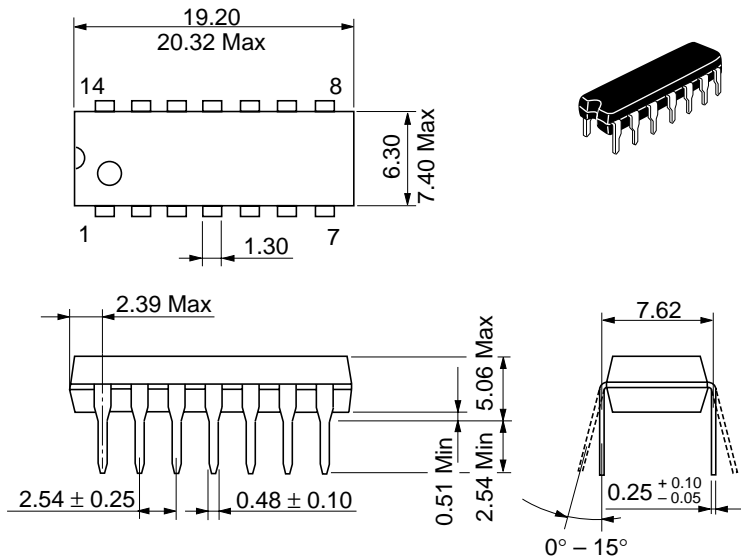
Item	Symbol	Test Conditions	min	typ*	max	Unit	
Input voltage	V_{IH}		2.0	—	—	V	
	V_{IL}		—	—	0.8	V	
Output voltage	V_{OL}	$V_{CC} = 4.75\text{V}, V_I = 2\text{V}$	$I_{OL} = 4\text{mA}$	—	—	0.4	V
			$I_{OL} = 8\text{mA}$	—	—	0.5	
Input current	I_{IH}	$V_{CC} = 5.25\text{V}, V_I = 2.7\text{V}$	—	—	20	μA	
	I_{IL}	$V_{CC} = 5.25\text{V}, V_I = 0.4\text{V}$	—	—	0.4	mA	
	I_I	$V_{CC} = 5.25\text{V}, V_I = 7\text{V}$	—	—	0.1	mA	
Output current	I_{OH}	$V_{CC} = 4.75\text{V}, V_{IL} = 0.8\text{V}$	$V_{OH} = 12\text{V}$	—	—	50	μA
			$V_{OH} = 15\text{V}$	—	—	1	mA
Supply current	I_{CCH}	$V_{CC} = 5.25\text{V}$	—	0.8	1.6	mA	
	I_{CCL}		—	2.4	4.4		
Input clamp voltage	V_{IK}	$V_{CC} = 4.75\text{V}, I_{IN} = -18\text{mA}$	—	—	-1.5	V	

* $V_{CC} = 5\text{V}, T_a = 25^\circ\text{C}$

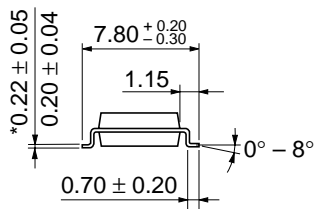
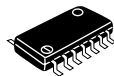
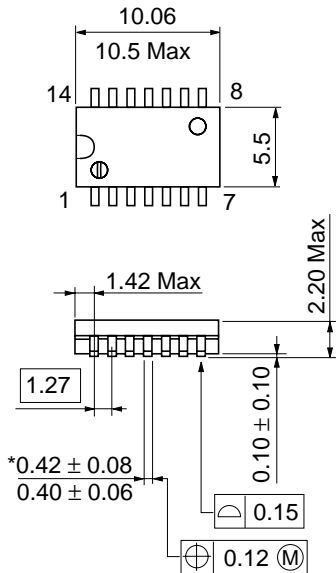
■ SWITCHING CHARACTERISTICS ($V_{CC} = 5\text{V}, T_a = 25^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	$C_L = 15\text{pF}, R_L = 2\text{k}\Omega$	—	17	32	ns
	t_{PHL}		—	15	28	

Note) Refer to Test Circuit and Waveform of the Common Item

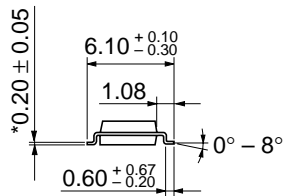
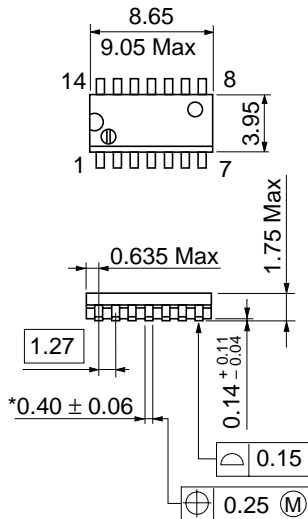


Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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